

**IN THE CLAIMS:**

Please substitute the following claims for the same numbered claims in the application:

1. (Currently Amended) An apparatus for holding a substrate, said apparatus comprising:  
a pocket adapted to hold said substrate, wherein said pocket ~~has~~ comprises an inner edge  
and a lower surface; and  
a plurality of projections extending radially inward from said inner edge[.];  
an opening in said lower surface;  
a pin disposed in said opening, said pin being configured for lifting said substrate from  
said pocket;  
wherein said projections have a beveled edge, such that an acute angle occurs between  
said lower surface and said beveled edge, and  
wherein said projections reduce an area of contact between said inner edge and said  
substrate.
2. (Original) The apparatus of claim 1, wherein said apparatus comprises a susceptor for  
wafer.
3. (Original) The apparatus of claim 1, wherein said apparatus includes at least two of said  
projections.
4. (Currently Amended) The apparatus of claim 1, wherein said projections have a "C"

10/064,451

2

shape when viewed from a top.

5. (Original) The apparatus of claim 1, wherein said projections maintain a gap between a sidewall of said substrate and said inner edge.
6. (Original) The apparatus of claim 1, wherein said acute angle comprises an angle between 80 and 85 degrees.
7. (Original) The apparatus of claim 1, wherein said projections prevent said substrate from moving within said pocket.
8. (Currently Amended) An apparatus for holding a substrate, said apparatus comprising:  
a pocket adapted to hold said substrate, wherein said pocket ~~has~~ comprises an inner edge and a lower surface; and  
a plurality of projections extending radially inward from said inner edge~~[[,]]~~; and  
an opening in said lower surface;  
wherein said projections have a beveled edge.
9. (Original) The apparatus in claim 8, wherein an acute angle occurs between a lower surface of said pocket and said beveled edge.
10. (Original) The apparatus in claim 8, wherein said projections reduce an area of contact

10/064,451

3

between said inner edge and said substrate.

11. (Original) The apparatus of claim 8, wherein said apparatus comprises a susceptor for wafer.
12. (Original) The apparatus of claim 8, wherein said apparatus includes at least two of said projections.
13. (Currently Amended) The apparatus of claim 8, wherein said projections have a "C" shape ~~when viewed from a top~~.
14. (Original) The apparatus of claim 8, wherein said projections maintain a gap between a sidewall of said substrate and said inner edge.
15. (Original) The apparatus of claim 9, wherein said acute angle comprises an angle between 80 and 85 degrees.
16. (Original) The apparatus of claim 8, wherein said projections prevent said substrate from moving within said pocket.
17. (Currently Amended) ~~[[An]]~~ A susceptor for holding a wafer, said susceptor comprising:  
a pocket adapted to hold said wafer, wherein said pocket ~~has~~ comprises an inner edge;

10/064,451

4

and

a plurality of projections extending radially inward from said inner edge[.]; and  
a device positioned below said pocket, said device being configured for lifting said wafer  
from said pocket;

wherein said projections have a beveled edge.

18. (Original) The susceptor in claim 17, wherein an acute angle occurs between a lower surface of said pocket and said beveled edge.
19. (Original) The susceptor of claim 17, wherein said susceptor includes at least two of said projections.
20. (Currently Amended) The susceptor of claim 17, wherein said projections have a "C" shape ~~when viewed from a top.~~